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## FDBL0150N80

# N-Channel PowerTrench<sup>®</sup> MOSFET 80 V, 300 A, 1.4 m $\Omega$

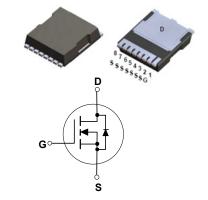
#### **Features**

- Typical  $R_{DS(on)}$  = 1.1 mΩ at  $V_{GS}$  = 10V,  $I_D$  = 80 A
- Typical  $Q_{q(tot)}$  = 172 nC at  $V_{GS}$  = 10V,  $I_D$  = 80 A
- UIS Capability
- RoHS Compliant

### **Applications**

- Industrial Motor Drive
- Industrial Power Supply
- Industrial Automation
- Battery Operated tools
- Battery Protection
- Solar Inverters
- UPS and Energy Inverters
- Energy Storage
- Load Switch





**July 2016** 

For current package drawing, please refer to the Fairchild website at https://www.fairchildsemi.com/evaluate/package-specifications/packageDetails.html?id=PN\_PSOFA-008

## **MOSFET Maximum Ratings** T<sub>J</sub> = 25°C unless otherwise noted.

Symbol	Parameter	Ratings	Units		
$V_{DSS}$	Drain-to-Source Voltage		80	V	
$V_{GS}$	Gate-to-Source Voltage		±20	V	
	Drain Current - Continuous (V <sub>GS</sub> =10) (Note 1)	T <sub>C</sub> = 25°C	300	Α	
ID	Pulsed Drain Current	T <sub>C</sub> = 25°C	See Figure 4	7	
E <sub>AS</sub>	Single Pulse Avalanche Energy	(Note 2)	820	mJ	
D	Power Dissipation		429	W	
$P_{D}$	Derate Above 25°C		2.86	W/°C	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature		-55 to + 175	°C	
$R_{\theta JC}$	Thermal Resistance, Junction to Case		0.35	°C/W	
$R_{\theta JA}$	Maximum Thermal Resistance, Junction to Ambient	(Note 3)	43	°C/W	

#### Notes

- 1: Current is limited by bondwire configuration.
- 2: Starting T<sub>J</sub> = 25°C, L = 0.4mH, I<sub>AS</sub> = 64A, V<sub>DD</sub> = 40V during inductor charging and V<sub>DD</sub> = 0V during time in avalanche.

  3: R<sub>0,JA</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder
- 3: R<sub>0,JA</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder mounting surface of the drain pins. R<sub>0,JC</sub> is guaranteed by design, while R<sub>0,JA</sub> is determined by the board design. The maximum rating presented here is based on mounting on a 1 in<sup>2</sup> pad of 2oz copper.

#### **Package Marking and Ordering Information**

Device Marking	Device	Package			
FDBL0150N80	FDBL0150N80	MO-299A	-	-	-

Units

Max.

Тур.

## **Electrical Characteristics** $T_J = 25^{\circ}C$ unless otherwise noted.

**Parameter** 

Off Characteristics							
B <sub>VDSS</sub>	Drain-to-Source Breakdown Voltage	I <sub>D</sub> = 250μA, V <sub>G</sub>	S = 0V	80	-	-	V
	Drain-to-Source Leakage Current	V <sub>DS</sub> =80V, T <sub>J</sub>	<sub>J</sub> = 25°C	-	-	1	μА
IDSS		$V_{GS} = 0V$ $T_J$	<sub>J</sub> = 175°C (Note 4)	-	-	1	mA
$I_{GSS}$	Gate-to-Source Leakage Current	V <sub>GS</sub> = ±20V		-	ı	±100	nA

**Test Conditions** 

Min.

## **On Characteristics**

Symbol

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$		2.0	3.0	4.0	V
R <sub>DS(on)</sub>	Drain to Source On Resistance	I <sub>D</sub> = 80A,	$T_{J} = 25^{\circ}C$	-	1.1	1.4	mΩ
		V <sub>GS</sub> = 10V	$T_J = 175^{\circ}C \text{ (Note 4)}$	-	2.4	3.1	mΩ

## **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	\/ OF\/ \/	V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V, f = 1MHz		12800	-	pF
C <sub>oss</sub>	Output Capacitance				1925	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 - 1101112			139	-	pF
$R_g$	Gate Resistance	f = 1MHz	f = 1MHz		3.0	4.6	Ω
$Q_{g(ToT)}$	Total Gate Charge at 10V	V <sub>GS</sub> = 0 to 10V	V <sub>DD</sub> = 64V	-	172	188	nC
Q <sub>g(th)</sub>	Threshold Gate Charge	$V_{GS} = 0$ to 2V	I <sub>D</sub> = 80A	-	23	27	nC
$Q_{gs}$	Gate-to-Source Gate Charge		_	-	51	-	nC
$Q_{ad}$	Gate-to-Drain "Miller" Charge			-	34	-	nC

## **Switching Characteristics**

t <sub>on</sub>	Turn-On Time		-	-	128	ns
t <sub>d(on)</sub>	Turn-On Delay		-	42	-	ns
t <sub>r</sub>	Rise Time	V <sub>DD</sub> = 40V, I <sub>D</sub> = 80A,	-	73	-	ns
t <sub>d(off)</sub>	Turn-Off Delay	$V_{GS}$ = 10V, $R_{GEN}$ = $6\Omega$	-	87	-	ns
t <sub>f</sub>	Fall Time		-	48	-	ns
t <sub>off</sub>	Turn-Off Time		-	-	193	ns

#### **Drain-Source Diode Characteristics**

V <sub>SD</sub>	Source-to-Drain Dioge Voltage	$I_{SD}$ =80A, $V_{GS}$ = 0V	-	-	1.25	V
		$I_{SD}$ = 40A, $V_{GS}$ = 0V	-	-	1.2	V
t <sub>rr</sub>	Reverse-Recovery Time	$I_F = 80A$ , $dI_{SD}/dt = 100A/\mu s$ ,	-	117	136	ns
Q <sub>rr</sub>	Reverse-Recovery Charge	$V_{DD}=64V$	-	205	269	nC

#### Note:

4: The maximum value is specified by design at  $T_J$  = 175°C. Product is not tested to this condition in production.

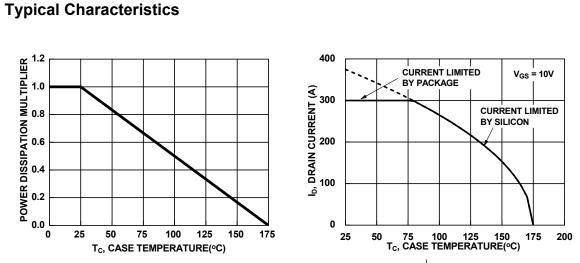
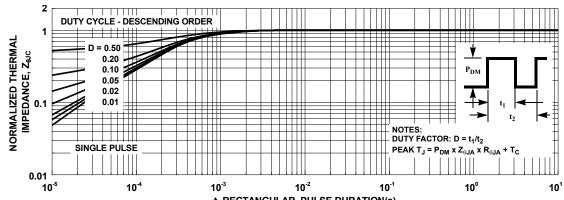


Figure 1. Normalized Power Dissipation vs. Case Temperature

Figure 2. Maximum Continuous Drain Current vs.

Case Temperature



t, RECTANGULAR PULSE DURATION(s)
Figure 3. Normalized Maximum Transient Thermal Impedance

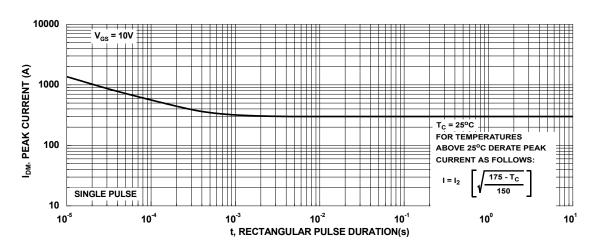


Figure 4. Peak Current Capability

## **Typical Characteristics**

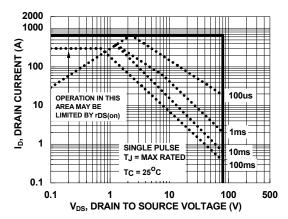
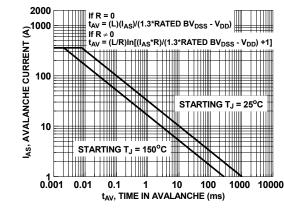


Figure 5. Forward Bias Safe Operating Area



NOTE: Refer to Fairchild Application Notes AN7514 and AN7515

Figure 6. Unclamped Inductive Switching Capability

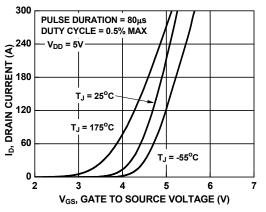


Figure 7. Transfer Characteristics

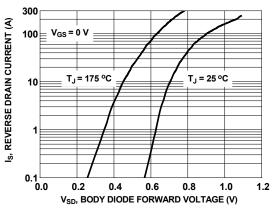


Figure 8. Forward Diode Characteristics

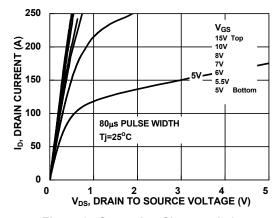


Figure 9. Saturation Characteristics

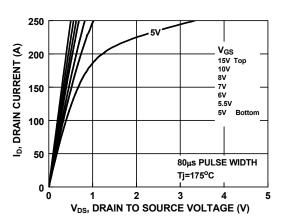


Figure 10. Saturation Characteristics

## **Typical Characteristics**

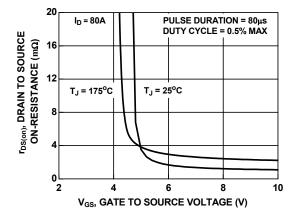


Figure 11. R<sub>DSON</sub> vs. Gate Voltage

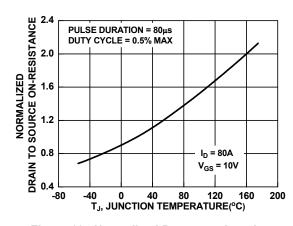


Figure 12. Normalized R<sub>DSON</sub> vs. Junction Temperature

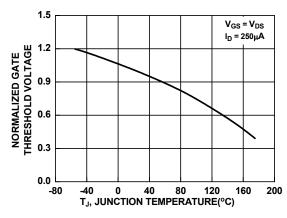


Figure 13. Normalized Gate Threshold Voltage vs. Temperature

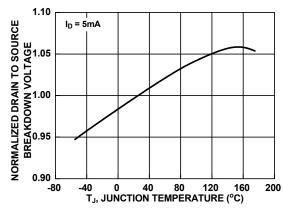


Figure 14. Normalized Drain to Source Breakdown Voltage vs. Junction Temperature

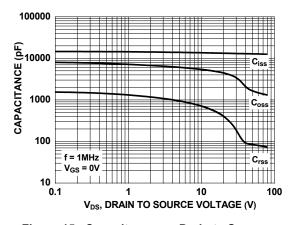


Figure 15. Capacitance vs. Drain to Source Voltage

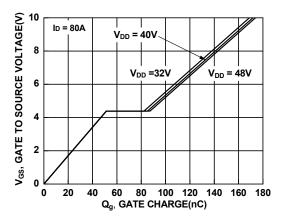
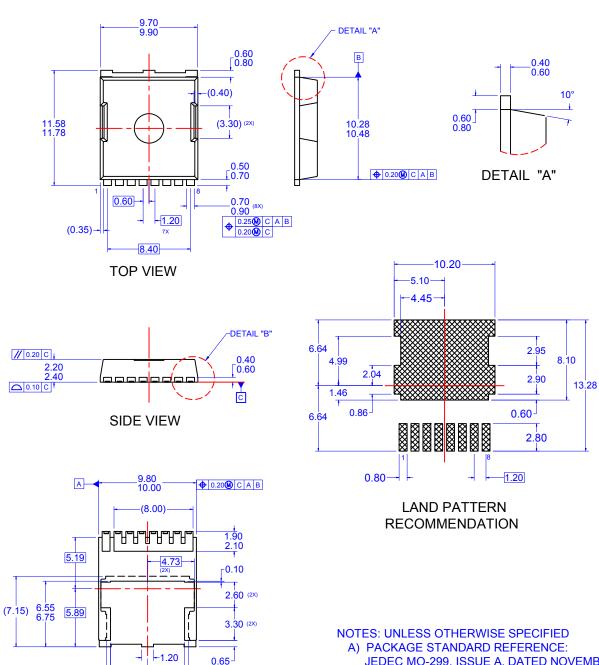


Figure 16. Gate Charge vs. Gate to Source Voltage



- JEDEC MO-299, ISSUE A, DATED NOVEMBER
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
- D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- E) DRAWING FILE NAME: MKT-PSOF08AREV3

-(8.30) **BOTTOM VIEW** 10° - (0.35)

3.75

7.60

0.65-

DETAIL "B"

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